In the Claims:

Please cancel claims 1-4 and 10-24. Please amend claim 5. The claims are as follows:

1-4. (Canceled)

5. (Currently amended) ~~A package according to claim 1, in which~~ An integrated circuit package, comprising:

an integrated circuit die; and

a set of circuit bond pads on the die connected to a set of package bond pads disposed on a first surface of the package, the package bond pads being arranged in a set of package bond pad modules such that at least one pair of individual package bond pads is disposed with a package bond pad module overlap in an overlap area along a transverse axis extending substantially perpendicular to the die, a first package bond pad of said pair being connected to a first via positioned inward of said overlap area and a second package bond pad of said pair being connected to a second via positioned outward of said overlap area, all of said first package bond pad, said first via, said second package bond pad and said second via being disposed within one of said package bond pad modules and forming a via submodule, each of said package bond pad modules having a package module pitch along a longitudinal axis parallel to a side of said integrated circuit die, wherein no connection for DC power passes along a conductive member that passes substantially parallel to a longitudinal axis substantially perpendicular to said transverse axis through substantially all of a subset of package bond pad modules on an edge of said die.

6. (Original) A package according to claim 5, in which at least one connection for DC power passes through a via submodule located along said transverse axis at a first position.

7. (Original) A package according to claim 6, in which at least two connections for DC power pass through a single via submodule located at a first position along said transverse axis.

8. (Original) A package according to claim 7, in which at least two connections for DC power pass through corresponding first and second via submodules located at said first position along said transverse axis and in separate package bond pad modules.

9. (Original) A package according to claim 6, in which no connection for DC power passes along a conductive member that passes substantially parallel to a longitudinal axis substantially perpendicular to said transverse axis through substantially all of a subset of package bond pad modules on an edge of said die.

10-24. (Canceled)